

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2000-156565
(43)Date of publication of application : 06.06.2000

(51)Int.Cl.

H05K 3/46

(21)Application number : 10-331200

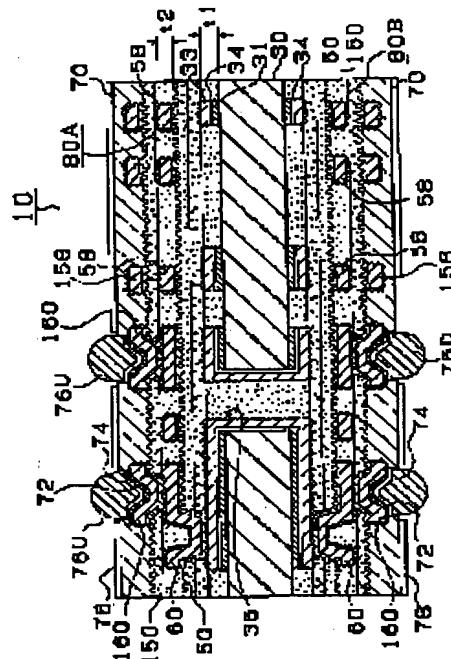
(71)Applicant : **IBIDEN CO LTD**
(72)Inventor : **NODA KOTA**

(54) MANUFACTURE OF MULTILAYER PRINTED WIRING BOARD, AND MULTILAYER PRINTED WIRING BOARD

(57) Abstract:

PROBLEM TO BE SOLVED: To make a multilayer printed wiring board into one excellent in high frequency property.

SOLUTION: A conductor circuit 34 is made by precipitating a plated film 33 after thinning the copper foil 31 of a laminate both whose sides are lined with copper by etching. An interlayer resin insulating layer 50 and a conductor layer 58 are stacked on the conductor circuit 34, but the total thickness of the copper foil 31 forming the conductor circuit 34 and the plated film 33 is small, and it is not greatly different from the thickness t_2 of the conductor layer 58 of the interlayer resin insulating layer 50, so the impedance of the conductor circuit 34 and that of the conductor layer 58 can be matched with each other, and it becomes possible to raise the performance in high frequency of the multilayer printed wiring board.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

BEST AVAILABLE COPY